

AMENDMENTS TO THE SPECIFICATION

Please replace the abstract of the specification with the following amended abstract:

-- An electronic component mounting method comprising: is disclosed, which includes: supplying an unhardened reinforcing resin on a circuit substrate; supplying a solder paste on bond areas of the circuit substrate on which electrodes of the electronic components are to be bonded; placing the electronic components on the circuit substrate; and heating and then cooling the circuit substrate with the reinforcing resin, the solder paste, and the electronic components carried thereon. The mounting method enables mounting of components with high joint reliability, while incorporating the conventional surface mount process shape. The method may also be applied to the mounting of smaller electronic components with narrower pitch without deteriorating productivity or mounting quality. --